UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATE OF CORRECTION

PATENT NO. : 5,397,432
DATED : March 10, 1995
INVENTOR(S) : Konno, et. Al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 11, line 39, delete "or" insert therefor --and --.

Column 10-11, Table 1, ~~insert symbols~~ should be deleted and substitute therefor, the attached Table 1.

~~See Continued Sheet~~

Table 1

Conditions	Amount of residual chlorine μm g/cm^2	10^{15}atoms/cm^2	After-corrosion	Symbols shown in Fig. 9
① Etching only	0.92±0.06	16.0±1.0	Large	○
② Downflow ashing using O_2 after ①	0.89±0.06	15.5±1.0	Large	●
③ Downflow ashing using O_2+CF_4 after ①	0.54±0.03	9.3±0.4	Small	■
④ Downflow ashing using O_2+H_2O after ①	0.23±0.03	4.0±0.5	No	◇
⑤ Exposure to H_2O after ② (30sec)	0.51±0.02	8.7±0.3	Small	▲
⑥ Exposure to H_2O after ② (90sec)	0.48±0.01	8.1±0.2	Small	▲
⑦ Exposure to H_2O after ② (180sec)	0.45±0.04	7.6±0.7	Small	▲
⑧ Downflow treatment using H_2O after ② (30sec)	0.28±0.01	4.7±0.2	None	Δ
⑨ Downflow treatment using H_2O after ② (90sec)	0.15±0.00	2.5±0.0	No	Δ
⑩ Downflow treatment using H_2O after ② (180sec)	0.11±0.01	1.9±0.1	No	Δ
⑪ Downflow treatment using H_2 after ② (30sec)	0.68±0.01	11.8±0.2	Small	▼
⑫ Downflow treatment using H_2O after ② (90sec)	0.68±0.01	11.7±0.1	Small	▼
⑬ Downflow treatment using H_2 after ② (180sec)	0.64±0.01	11.1±0.2	Small	▼

Exposure to H_2O: heated at 120°C in water vapor at 0.1 Torr.